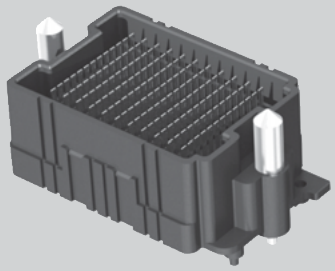
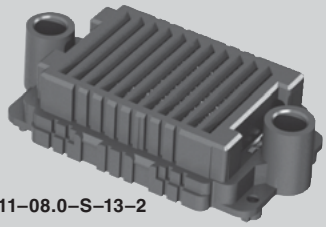
F-215 SUPPLEMENT

samtec

HD MEZZ



HDAM–11–12.0–S–13–2



HDAF–11–08.0–S–13–2

(2,00 mm) .0787"

HDAM, HDAF SERIES

RUGGED ELEVATED HIGH DENSITY ARRAY

HDAM Mates with:
HDAF

HDAF Mates with:
HDAM

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?HDAM or www.samtec.com?HDAF

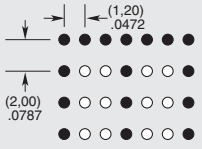
Insulator Material:
Black LCP
Contact Material:
Copper Alloy
Plating:
Au or Sn over
50µ" (1,27 µm) Ni
Current Rating:
3.4 A per pin
(6 adjacent pins powered)
Operating Temp Range:
-55°C to +125°C
Contact Resistance: 19 mΩ
Working Voltage: 200 VAC
Mated Cycles: 100
RoHS Compliant: Yes
Lead-Free Solderable: Yes

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality

FILE NO. E111594

DIFFERENTIAL APPLICATIONS



ARRAY	PAIR COUNT*
11x13	44
15x13	60
23x13	92

*2:1 S:G Ratio

ALSO AVAILABLE
(MOQ Required)

- Tin-Lead Solder Charge
- Other platings

Contact Samtec.

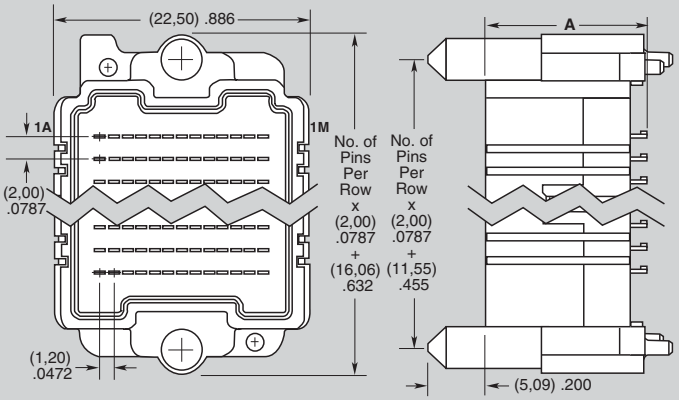
Note: HD Mezz is a trademark of Molex Incorporated

Note: Some lengths, styles and options are non-standard, non-returnable.

HDAM – NO. OF PINS PER ROW – LEAD STYLE – PLATING OPTION – NO. OF ROWS – SOLDER TYPE – OTHER OPTION

- NO. OF PINS PER ROW: –11, –15, –23
- LEAD STYLE: Specify LEAD STYLE from chart
- PLATING OPTION: –S = 30µ" (0,76 µm) Gold on contact area, Matte Tin on tails and guide pins
- NO. OF ROWS: –13
- SOLDER TYPE: –2 = Lead-Free Tin Alloy 95.5% Sn/ 3.8% Ag/0.7% Cu Solder Charge
- OTHER OPTION: –P = Pick & Place Pad

Final Inch® CERTIFIED Patent Pending



LEAD STYLE	A
–12.0	(14,41) .567
–17.0	(19,41) .764

RUGGEDIZED by SAMTEC
- Integrated guide posts

HDAM/HDAF 35 mm Stack Height	Rated @ 3dB Insertion Loss*
Single-Ended Signaling	9 GHz / 18 Gbps
Differential Pair Signaling	9 GHz / 18 Gbps

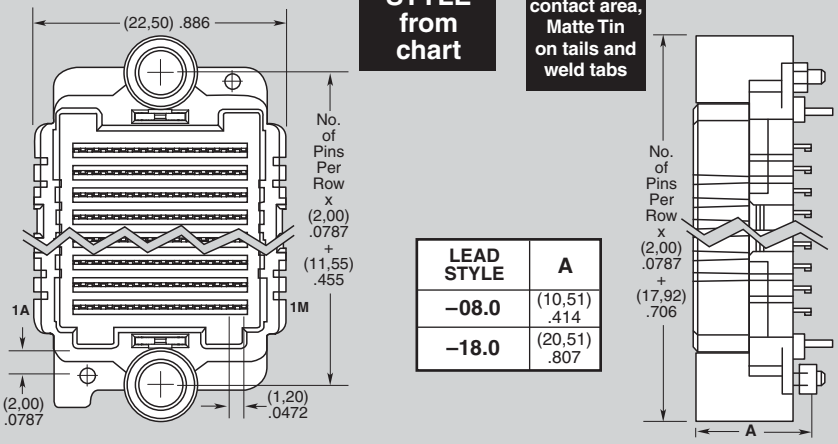
*Data based on simulations using Final Inch® design.

*Performance data includes effects of a non-optimized PCB.

Performance data for other stack heights and complete test data available at www.samtec.com?HDAM, www.samtec.com?HDAF or contact sig@samtec.com

HDAF – NO. OF PINS PER ROW – LEAD STYLE – PLATING OPTION – NO. OF ROWS – SOLDER TYPE – OTHER OPTION

- NO. OF PINS PER ROW: –11, –15, –23
- LEAD STYLE: Specify LEAD STYLE from chart
- PLATING OPTION: –S = 30µ" (0,76 µm) Gold on contact area, Matte Tin on tails and weld tabs
- NO. OF ROWS: –13
- SOLDER TYPE: –2 = Lead-Free Tin Alloy 95.5% Sn/ 3.8% Ag/ 0.7% Cu Solder Charge
- OTHER OPTION: –P = Pick & Place Pad



LEAD STYLE	A
–08.0	(10,51) .414
–18.0	(20,51) .807

RUGGEDIZED by SAMTEC
- Integrated guide posts